

ON Semiconductor®

BSS138

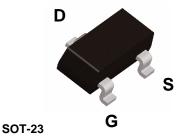
N-Channel Logic Level Enhancement Mode Field Effect Transistor

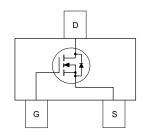
General Description

These N-Channel enhancement mode field effect transistors are produced using ON Semicondcutor's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- 0.22 A, 50 V. $R_{DS(ON)} = 3.5\Omega$ @ $V_{GS} = 10$ V $R_{DS(ON)} = 6.0\Omega$ @ $V_{GS} = 4.5$ V
- High density cell design for extremely low R_{DS(ON)}
- Rugged and Reliable
- Compact industry standard SOT-23 surface mount package





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain-Source Voltage		50	V	
V _{GSS}	Gate-Source Voltage		±20	V	
I _D	Drain Current - Continuous	(Note 1)	0.22	A	
	– Pulsed		0.88		
P _D	Maximum Power Dissipation	(Note 1)	0.36	W	
	Derate Above 25°C		2.8	mW/°C	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds		300	°C	

Thermal Characteristics

R _{6JA} Thermal Resistance, Junction-to-Ambient (Note 1) 350 °C/W
--

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
SS	BSS138	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics		I			
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	50			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A,Referenced to 25°C		72		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 50 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			0.5	μΑ
		$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V T}_{J} = 125^{\circ}\text{C}$			5	μΑ
		$V_{DS} = 30 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			100	nA
I _{GSS}	Gate-Body Leakage.	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1 \text{ mA}$	0.8	1.3	1.5	V
$rac{\Delta {\sf V}_{\sf GS(th)}}{\Delta {\sf T}_{\sf J}}$	Gate Threshold Voltage Temperature Coefficient	I _D = 1 mA,Referenced to 25°C		-2		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$ \begin{vmatrix} V_{GS} = 10 \text{ V}, & I_D = 0.22 \text{ A} \\ V_{GS} = 4.5 \text{ V}, & I_D = 0.22 \text{ A} \\ V_{GS} = 10 \text{ V}, I_D = 0.22 \text{ A}, T_J = 125 ^{\circ}\text{C} \\ \end{vmatrix} $		0.7 1.0 1.1	3.5 6.0 5.8	Ω
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, \qquad V_{DS} = 5 \text{ V}$	0.2			Α
g FS	Forward Transconductance	$V_{DS} = 10V$, $I_{D} = 0.22 \text{ A}$	0.12	0.5		S
Dvnamic	Characteristics			•		
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		27		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		13		pF
C _{rss}	Reverse Transfer Capacitance			6		pF
R _G	Gate Resistance	$V_{GS} = 15 \text{ mV}, f = 1.0 \text{ MHz}$		9		Ω
Switchin	g Characteristics (Note 2)			•		
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, \qquad I_{D} = 0.29 \text{ A},$		2.5	5	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		9	18	ns
t _{d(off)}	Turn-Off Delay Time			20	36	ns
t _f	Turn-Off Fall Time	1		7	14	ns
Q_g	Total Gate Charge	$V_{DS} = 25 \text{ V}, \qquad I_{D} = 0.22 \text{ A},$		1.7	2.4	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		0.1		nC
Q_{gd}	Gate-Drain Charge	1		0.4		nC
Drain-So	ource Diode Characteristics	and Maximum Ratings	•	•		
l _s	Maximum Continuous Drain–Source				0.22	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \qquad I_S = 0.44 \text{ A(Note 2)}$		0.8	1.4	V

Notes:

R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.



a) 350°C/W when mounted on a minimum pad..

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

Typical Characteristics

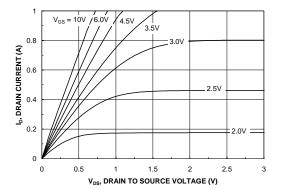


Figure 1. On-Region Characteristics.

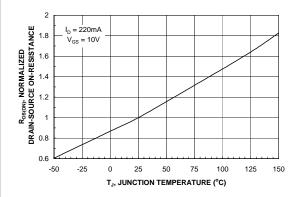


Figure 3. On-Resistance Variation with Temperature.

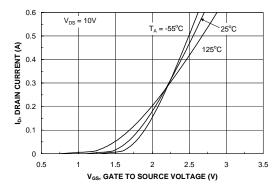


Figure 5. Transfer Characteristics.

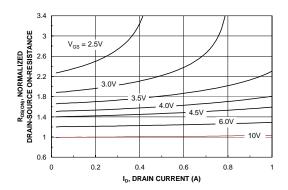


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

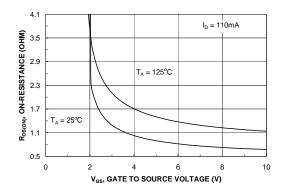


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

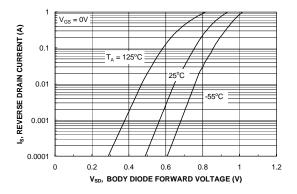
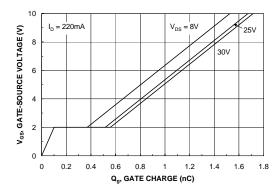


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



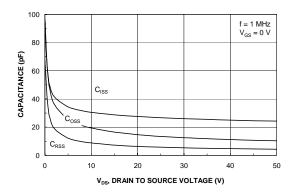


Figure 7. Gate Charge Characteristics.

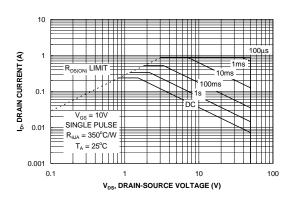


Figure 8. Capacitance Characteristics.

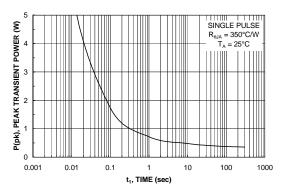


Figure 9. Maximum Safe Operating Area.



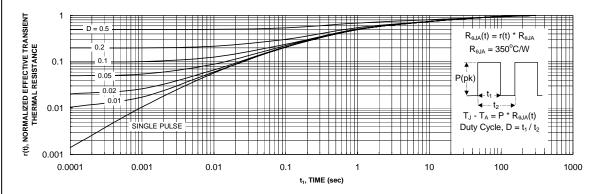


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1a. Transient thermal response will change depending on the circuit board design.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:
BSS138 BSS138-G